



# EurosimE 2011

## CALL FOR PAPERS

**Thermal, Mechanical & Multiphysics Simulation and Experiments in Micro/Nano-Electronics and Microsystems**

**17-20 April, 2011, Linz, Austria**

### **The Conference**

After eleven successful editions of the EuroSimE conference, the twelfth edition, EuroSimE2011, is to be hosted in the beautiful Austrian town of **Linz**. The conference will address the results of both fundamental research and industrial applications for **thermal, mechanical** and **multiphysics** simulation and experiments of micro/nano-electronics and microsystems. The conference will include keynote presentations and sessions with a wide range of topics including, but not limited to:

#### **Subjects:**

- Multi-physics simulation (e.g., thermal, mechanical, thermo-mechanical, coupled thermo-fluidic, coupled electro-mechanics, fluid-structure interactions)
- Failure analysis and failure mode extraction
- Material characterisation, experiments and modelling
- Validation of simulations by experiments
- Failure criteria and damage modelling for reliability prediction
- Integrated process modelling
- Advanced numerical and analytical simulation methodologies and tools
- Behavioural modelling
- Simulation-based optimisation, virtual prototyping in product and/or process design
- Compact modeling and model order reduction

#### **Applications:**

- Components and packaging (flip-chip, BGA, CSP, Wafer-Level packages, MCM, Cu/low-k packages)
- 3-D packaging
- Opto-electronic packages
- High temperature and high power packaging
- Piezoelectric components
- Packaging for harsh environments
- "More than Moore" applications (e.g., SiP, Microsystems, MEMS, sensors actuators, MOEMS)
- Wafer processing, chip design and reliability
- Nano-electronics
- PWB design and applications
- Bio-electronics, bio-MEMS/NEMS and microfluidics
- LED lighting

### **Conference features**

- **Short courses** will be offered for professional training. The topics will be confirmed at a later stage.
- Three days of **technical sessions** for oral and poster presentations.
- A parallel **exhibition** from suppliers of experimental characterization equipment, and simulation and optimization software.
- Industrial keynote presentations from **Michael Mayer** (professor at University of Waterloo), Dr. **Martin Schrems** (Director Process Development and Implementation at Austriamicrosystems) and DI **Manfred Haas** (Vice President and Managing Director at Infineon Austria) are planned for the opening session.

### **To Submit an Abstract**

You are invited to submit an abstract of approximately 500 words describing the scope, contents, and key points (i.e., originality, specific results and potential impact).

Upload your abstract at <http://www.eurosimE.org/>

**Deadline extension for abstract submission:  
Sunday November 14th 2010**

Abstracts must be received by **Novemb. 14, 2010**. Authors will be notified of abstract acceptance by **December 18, 2010**. The deadline for submission of the final manuscripts is **March 1, 2011**.

**The best conference papers will be selected for possible publication in peer-reviewed journals (IEEE-CPMT & Elsevier's Micro-electronics Journal)**

**[www.eurosimE.org](http://www.eurosimE.org)**